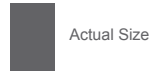
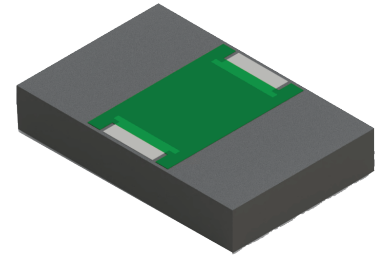


RM2335ZZ-XXXXWN-2U-02 Features:

- Single-Sided Terminals w/ Backplane Configuration
- Solder, Epoxy or Wirebondable Terminals
- Solder or Epoxy Mount Backplane
- Customer Defined Testing Available
- RoHS Compliant or SnPb Available
- Non-Magnetic Available
- Tape & Reel and Waffle Pack Available (Standard is bulk)

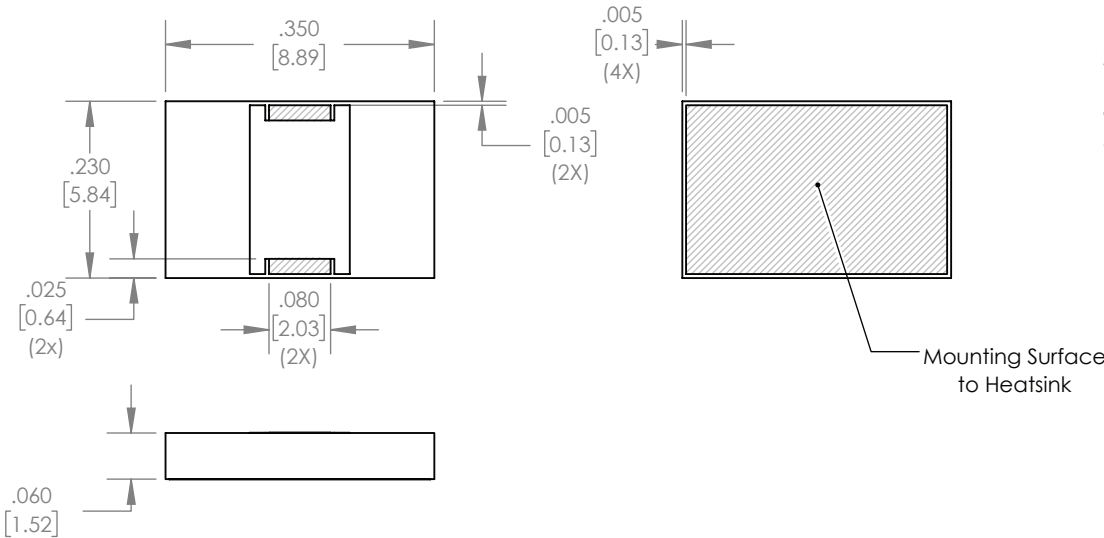


RM2335ZZ-XXXXWN-2U-02 Parameters:

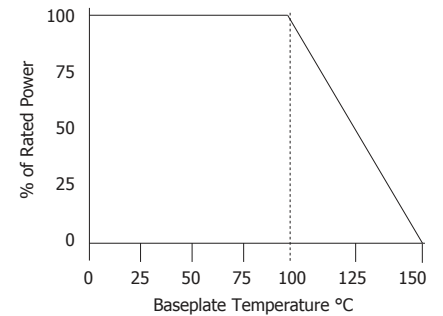
Resistance Range: 10Ω - 1KΩ
 Rated Power:* 50W
 Construction: Thick Film on 0.060" AlN
 Operating Temperature: -55 to +150°C

* Rating based on ≤100°C constant baseplate temperature

RM2335ZZ-XXXXWN-2U-02 Dimensions:



**RM2335ZZ-XXXXWN-2U-02
Power Derating Curve**



Dimensions in inches [mm]
 Tolerance is ± 0.005 [0.13]
 unless otherwise stated

Ordering Information:

Example Part Number: RM2335CT-50R0JN-2U-02

RM	2335	ZZ	-	XXXX	W	N	-	2U	-02	UU
Prefix for Resistor w/ Single-Sided Terminals and Backplane	Size 2335	Value Code 50R0 - 50Ω 1000 - 100Ω 1001 - 1KΩ		Tolerance F - 1% G - 2% J - 5%		Normal Inspection Contact factory for additional options		Substrate 2U - 0.060" AlN	Assigned by Factory	Packaging Blank - Bulk WP - Waffle Pack TR - Tape & Reel

Terminal Metallization

CB -	Tin Lead over Nickel over Silver
CC -	100% Matte Tin over Copper over Silver
CT -	100% Matte Tin over Nickel over Silver
GA -	Gold

	RoHS	Magnetic	Solder	Epoxy	Wirebond
	No	Yes	Yes	No	No
	Yes	No	Yes	No	No
	Yes	Yes	Yes	No	No
	Yes	No	No	Yes	Yes

Barry Industries reserves the right to change part number and/or process without notification.

RM2335ZZ-XXXXWN-2U-02 Reliability Specifications:

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 Para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202-210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65 to +150 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

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